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Kind regards,

Team Nexperia



PNTC123EMB

NPN resistor-equipped transistor; $R1 = 2.2\text{ k}\Omega$, $R2 = 2.2\text{ k}\Omega$

Rev. 1 — 3 April 2012

Product data sheet

1. Product profile

1.1 General description

NPN Resistor-Equipped Transistor (RET) in a leadless ultra small DFN1006B-3 (SOT883B) Surface-Mounted Device (SMD) plastic package.

PNP complement: PDTA123EMB.

1.2 Features and benefits

- 100 mA output current capability
- Reduces component count
- Built-in bias resistors
- Reduces pick and place costs
- Simplifies circuit design
- AEC-Q101 qualified
- Leadless ultra small SMD plastic package
- Low package height of 0.37 mm

1.3 Applications

- Low-current peripheral driver
- Control of IC inputs
- Replaces general-purpose transistors in digital applications
- Mobile applications

1.4 Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{CEO}	collector-emitter voltage	open base	-	-	50	V
I_O	output current		-	-	100	mA
R1	bias resistor 1 (input)	$T_{amb} = 25\text{ }^{\circ}\text{C}$	1.54	2.2	2.86	$\text{k}\Omega$
R2/R1	bias resistor ratio		0.8	1	1.2	



2. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	I	input (base)	 SOT883B (DFN1006B-3)	
2	G	GND (emitter)		
3	O	output (collector)		

3. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
PDTC123EMB	DFN1006B-3	Leadless ultra small plastic package; 3 solder lands; body 1.0 x 0.6 x 0.37 mm	SOT883B

4. Marking

Table 4. Marking codes

Type number	Marking code
PDTC123EMB	0011 0011

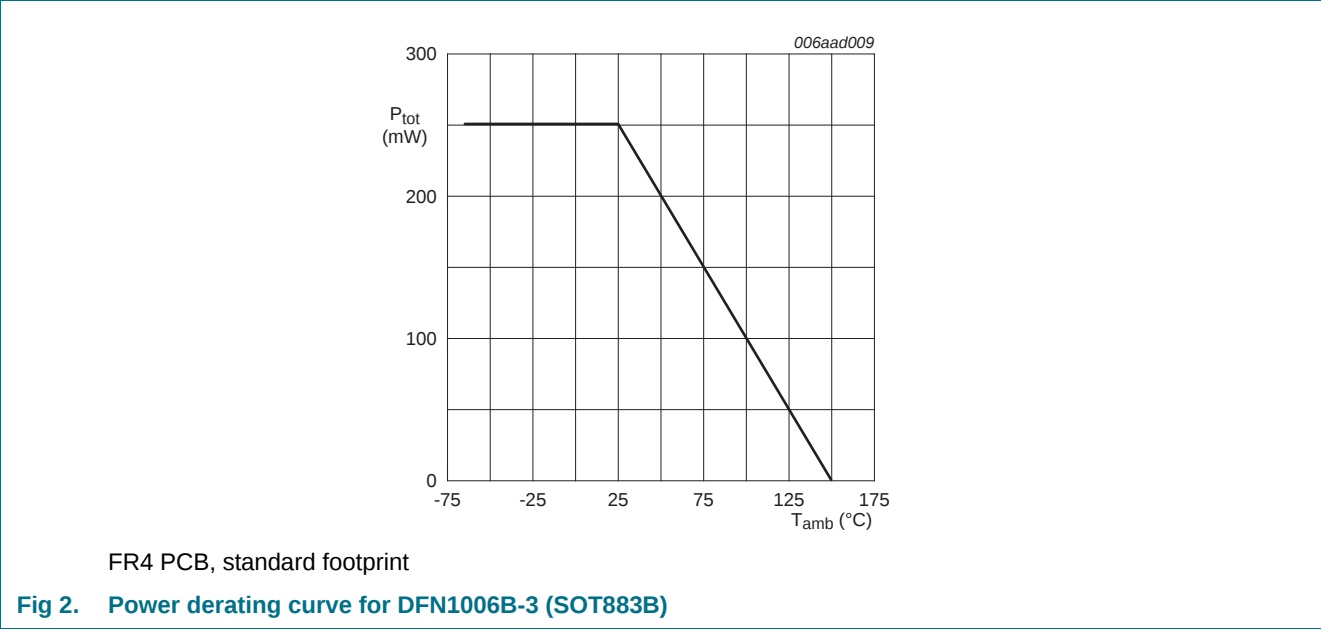


5. Limiting values

Table 5. Limiting values
In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V _{CBO}	collector-base voltage	open emitter	-	50	V
V _{CEO}	collector-emitter voltage	open base	-	50	V
V _{EBO}	emitter-base voltage	open collector	-	10	V
V _I	input voltage	positive	-	12	V
		negative	-	-10	V
I _O	output current		-	100	mA
I _{CM}	peak collector current	pulsed; t _p ≤ 1 ms	-	100	mA
P _{tot}	total power dissipation	T _{amb} ≤ 25 °C	[1][2]	250	mW
T _j	junction temperature		-	150	°C
T _{amb}	ambient temperature		-65	150	°C
T _{stg}	storage temperature		-65	150	°C

- [1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.
[2] Reflow soldering is the only recommended soldering method.

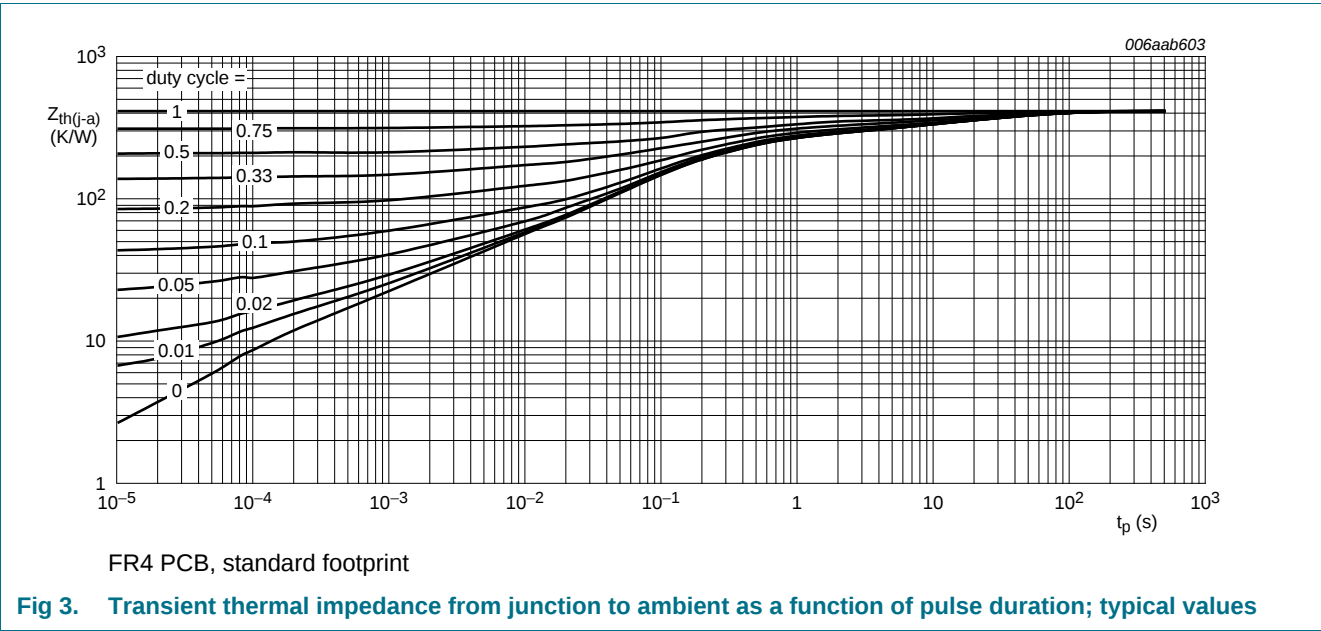


6. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	-	-	500	K/W

- [1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
[2] Reflow soldering is the only recommended soldering method.

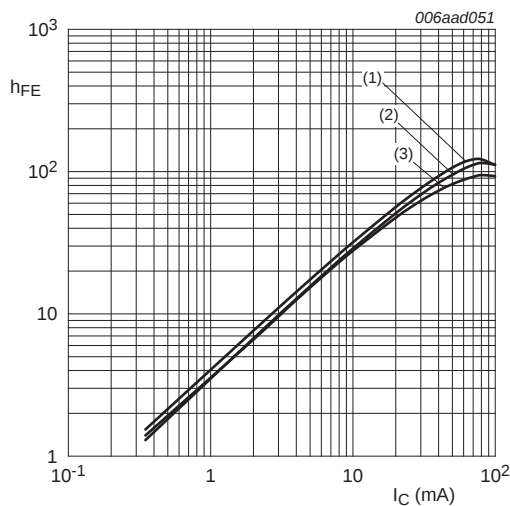


7. Characteristics

Table 7. Characteristics

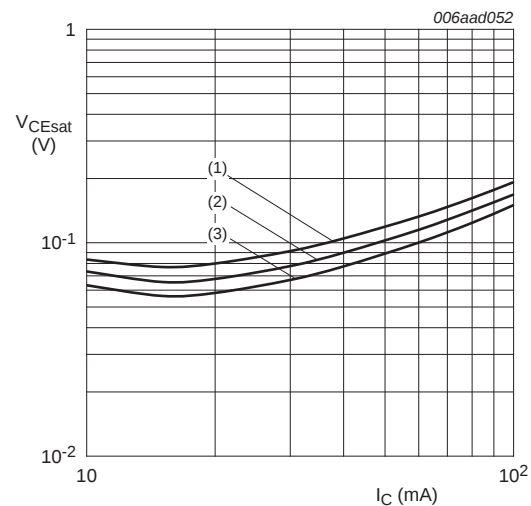
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
I_{CBO}	collector-base cut-off current	$V_{CB} = 50 \text{ V}$; $I_E = 0 \text{ A}$; $T_{amb} = 25 \text{ }^{\circ}\text{C}$	-	-	100	nA
I_{CEO}	collector-emitter cut-off current	$V_{CE} = 30 \text{ V}$; $I_B = 0 \text{ A}$; $T_{amb} = 25 \text{ }^{\circ}\text{C}$	-	-	1	μA
		$V_{CE} = 30 \text{ V}$; $I_B = 0 \text{ A}$; $T_j = 150 \text{ }^{\circ}\text{C}$	-	-	5	μA
I_{EBO}	emitter-base cut-off current	$V_{EB} = 5 \text{ V}$; $I_C = 0 \text{ A}$; $T_{amb} = 25 \text{ }^{\circ}\text{C}$	-	-	2	mA
h_{FE}	DC current gain	$V_{CE} = 5 \text{ V}$; $I_C = 20 \text{ mA}$; $T_{amb} = 25 \text{ }^{\circ}\text{C}$	30	-	-	
V_{CEsat}	collector-emitter saturation voltage	$I_C = 10 \text{ mA}$; $I_B = 0.5 \text{ mA}$; $T_{amb} = 25 \text{ }^{\circ}\text{C}$	-	-	150	mV
$V_{I(off)}$	off-state input voltage	$V_{CE} = 5 \text{ V}$; $I_C = 1 \text{ mA}$; $T_{amb} = 25 \text{ }^{\circ}\text{C}$	-	1.2	0.5	V
$V_{I(on)}$	on-state input voltage	$V_{CE} = 0.3 \text{ V}$; $I_C = 20 \text{ mA}$; $T_{amb} = 25 \text{ }^{\circ}\text{C}$	2	1.6	-	V
R1	bias resistor 1 (input)	$T_{amb} = 25 \text{ }^{\circ}\text{C}$	1.54	2.2	2.86	kΩ
R2/R1	bias resistor ratio		0.8	1	1.2	
C_C	collector capacitance	$V_{CB} = 10 \text{ V}$; $I_E = 0 \text{ A}$; $i_e = 0 \text{ A}$; $f = 1 \text{ MHz}$; $T_{amb} = 25 \text{ }^{\circ}\text{C}$	-	-	2.5	pF
f_T	transition frequency	$V_{CE} = 5 \text{ V}$; $I_C = 10 \text{ mA}$; $f = 100 \text{ MHz}$; $T_{amb} = 25 \text{ }^{\circ}\text{C}$	[1]	230	-	MHz

[1] Characteristics of built-in transistor.



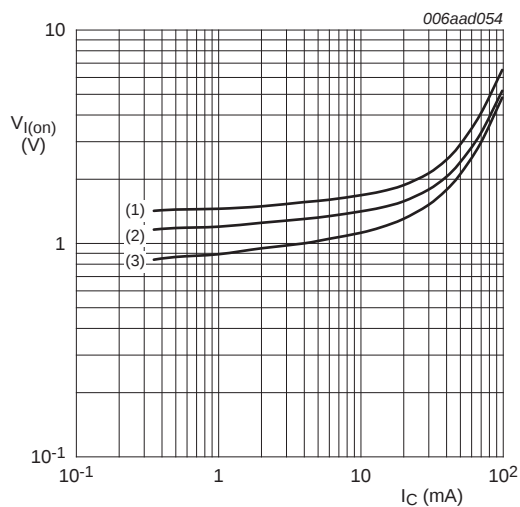
$V_{CE} = 5 \text{ V}$
 (1) $T_{amb} = 100 \text{ }^{\circ}\text{C}$
 (2) $T_{amb} = 25 \text{ }^{\circ}\text{C}$
 (3) $T_{amb} = -40 \text{ }^{\circ}\text{C}$

Fig 4. DC current gain as a function of collector current; typical values



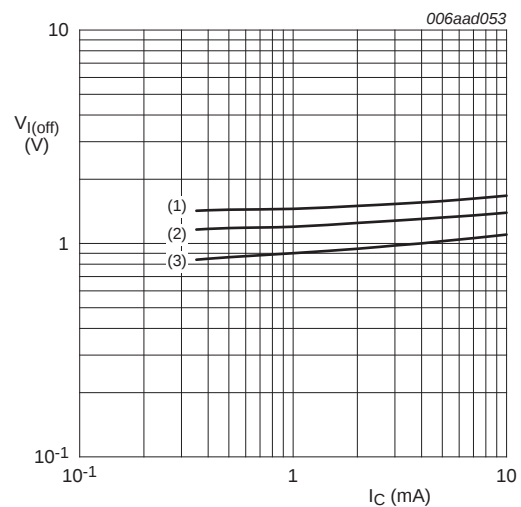
$I_C/I_B = 20$
 (1) $T_{amb} = 100 \text{ }^{\circ}\text{C}$
 (2) $T_{amb} = 25 \text{ }^{\circ}\text{C}$
 (3) $T_{amb} = -40 \text{ }^{\circ}\text{C}$

Fig 5. Collector-emitter saturation voltage as a function of collector current; typical values



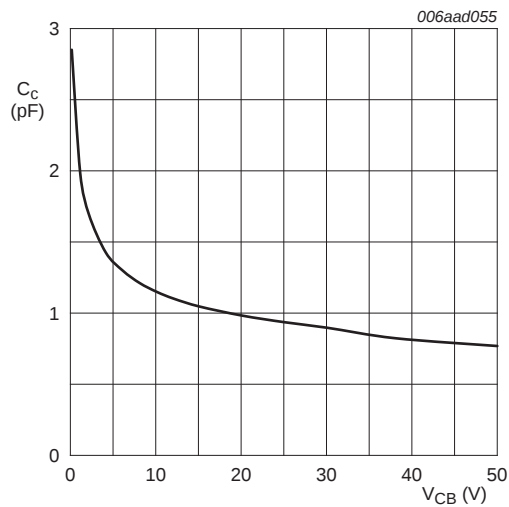
$V_{CE} = 0.3$ V
(1) $T_{amb} = -40$ °C
(2) $T_{amb} = 25$ °C
(3) $T_{amb} = 100$ °C

Fig 6. On-state input voltage as a function of collector current; typical values



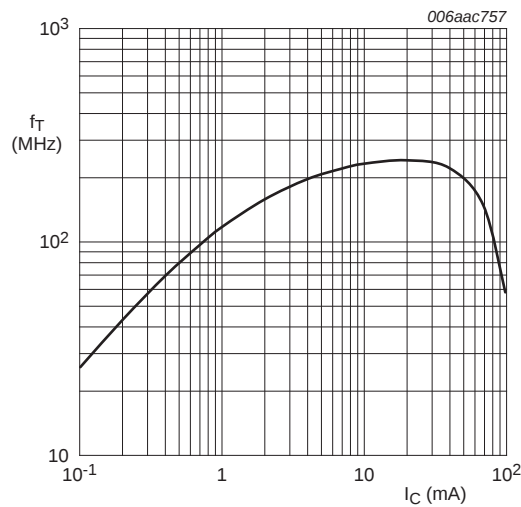
$V_{CE} = 5$ V
(1) $T_{amb} = -40$ °C
(2) $T_{amb} = 25$ °C
(3) $T_{amb} = 100$ °C

Fig 7. Off-state input voltage as a function of collector current; typical values



$f = 1$ MHz; $T_{amb} = 25$ °C

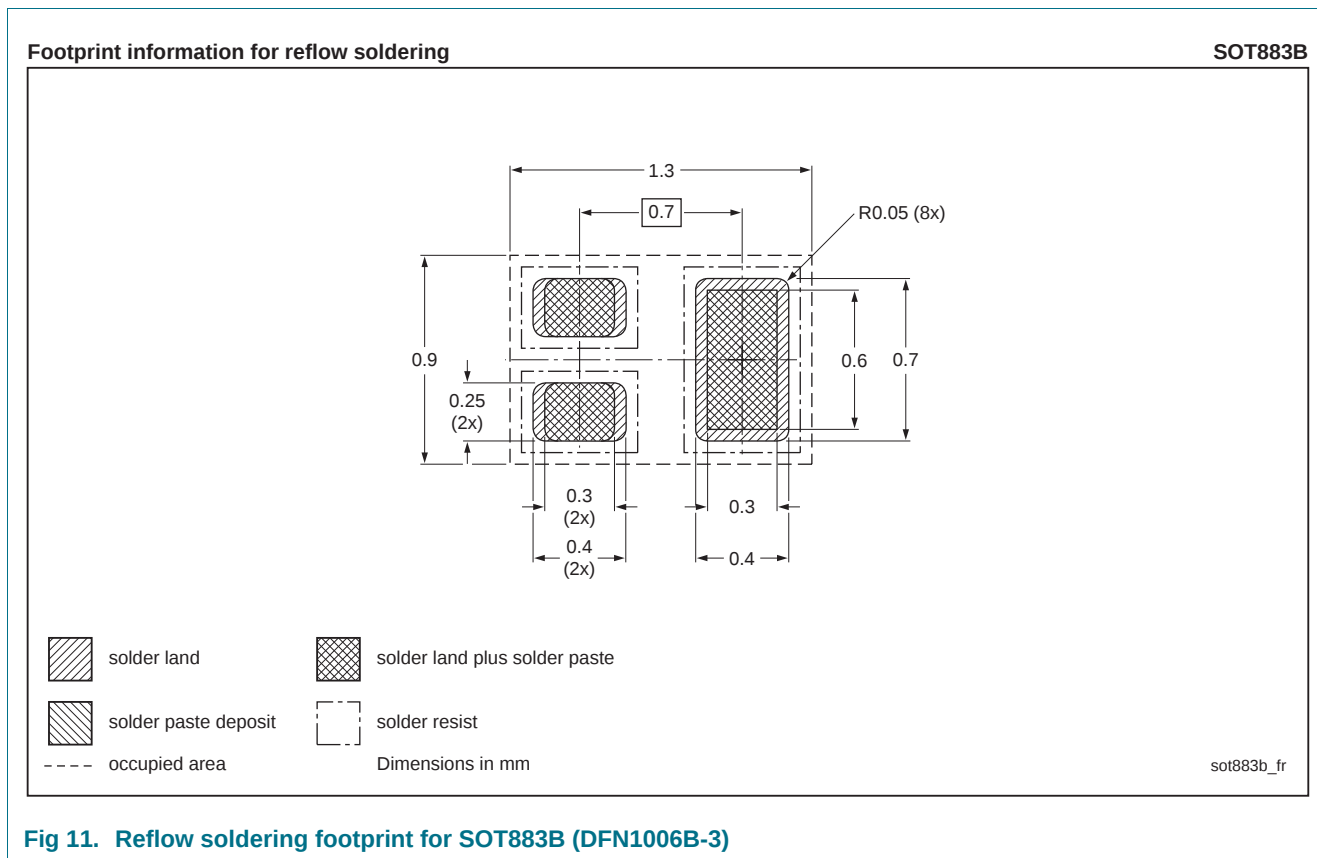
Fig 8. Collector capacitance as a function of collector-base voltage; typical values of built-in transistor



$V_{CE} = 5$ V; $T_{amb} = 25$ °C

Fig 9. Transition frequency as a function of collector current; typical values of built-in transistor

10. Soldering



11. Revision history

Table 8. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
PDTC123EMB v.1	20120403	Product data sheet	-	-

12. Legal information

12.1 Data sheet status

Document status ^{[1] [2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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[2] The term 'short data sheet' is explained in section "Definitions".

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